





## Pin Configuration

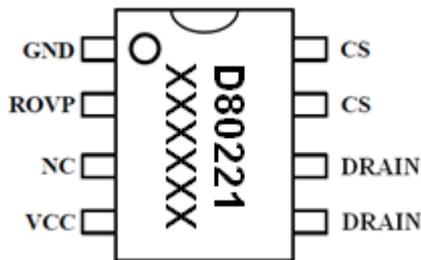


Figure 2. Pin configuration

## Pin Definition

Pin No.	Name	Description
1	GND	Ground
2	ROVP	Over Voltage Protection Setting Pin. Connect a resistor to GND
3	NC	No Connection. Should be connected to GND(Pin1)
4	VCC	Power Supply Pin
5.6	DRAIN	Internal HV Power MOSFET Drain.
7.8	CS	Current Sense Pin. Connect a sense resistor between this pin and GND pin.

## Absolute Maximum Ratings (note1)

Symbol	Parameters	Range	Units
ICC_MAX	VCC pin maximum sink current	5	mA
DRAIN	Internal HV MOSFET drain voltage	-0.3~500	V
CS	Current sense pin input voltage	-0.3~6	V
ROVP	Over-voltage setting pin voltage	-0.3~6	V
PDMAX	Power dissipation (note 2)	0.45	W
$\theta_{JA}$	Thermal resistance (Junction to Ambient)	145	$^{\circ}\text{C}/\text{W}$
TJ	Operating junction temperature	-40 to 150	$^{\circ}\text{C}$
TSTG	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

Note 1: Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. Under “recommended operating conditions” the device operation is assured, but some particular parameter may not be achieved. The electrical characteristics table defines the operation range of the device, the electrical characteristics is assured on DC and AC voltage by test program. For the parameters without minimum and maximum value in the EC table, the typical value defines the operation range, the accuracy is not guaranteed by spec.

Note 2: The maximum power dissipation decrease if temperature rise, it is decided by TJMAX,  $\theta_{JA}$ , and environment temperature (TA). The maximum power dissipation is the lower one between PDMAX = (TJMAX - TA)/  $\theta_{JA}$  and the number listed in the maximum table.

## Recommended Operation Conditions



Symbol	Parameter	Range	Unit
ILED1	Output LED current @ Vout=72V (Input voltage 176V~265V)	160	mA
ILED2	Output LED current @ Vout=36V (Input voltage 176V~265V)	220	mA
VLED min	Minimum LED Loading Voltage	>15	V

## Electrical Characteristics (Notes 4, 5) (Unless otherwise specified, VCC=15V and TA =25 °C)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Supply Voltage Section						
VCC_CLAMP	VCC Clamp Voltage	1mA		16.8		V
VCC_ON	VCC Turn On Threshold	VCC Rising		13.8		V
VCC_UVLO	VCC Turn off Threshold	VCC Falling		9		V
IST	VCC Startup Current	VCC= VCC-ON - 1V		120	180	uA
IOP	VCC Operating Current	FOP=70KHz		100	150	uA
Current Sense Section						
VCS_TH	Threshold Voltage for Peak Current Limit		388	400	412	mV
VCS_SHORT	Threshold Voltage for Peak Current Limit When Output Short			200		mV
TLEB	Leading Edge Blanking Time for Current Sense	Output Short		350		ns
TDELAY	Switch Off Delay Time			200		ns
Internal Time Control Section						
TOFF_MIN	Minimum OFF Time			4.5		us
TOFF_MAX	Maximum OFF Time			240		us
TON_MAX	Maximum On Time			40		us
VROVP	ROVP Pin Voltage			0.5		V
MOSFET Section						
RDS_ON	Static Drain-source On-resistance	VGS=15V/IDS=0.4A		14		Ω
BVDSS	Drain-Source Breakdown Voltage	VGS=0V/IDS=250uA	500			V
IDSS	Power MOSFET Drain Leakage Current	VGS=0V/VDS=500V			1	uA
Thermal Regulation Section						
TREG	Thermal Regulation Temperature			150		°C

Note 4: production testing of the chip is performed at 25°C.



Note 5: the maximum and minimum parameters specified are guaranteed by test, the typical value are guaranteed by design, characterization and statistical analysis.

## Internal Block Diagram

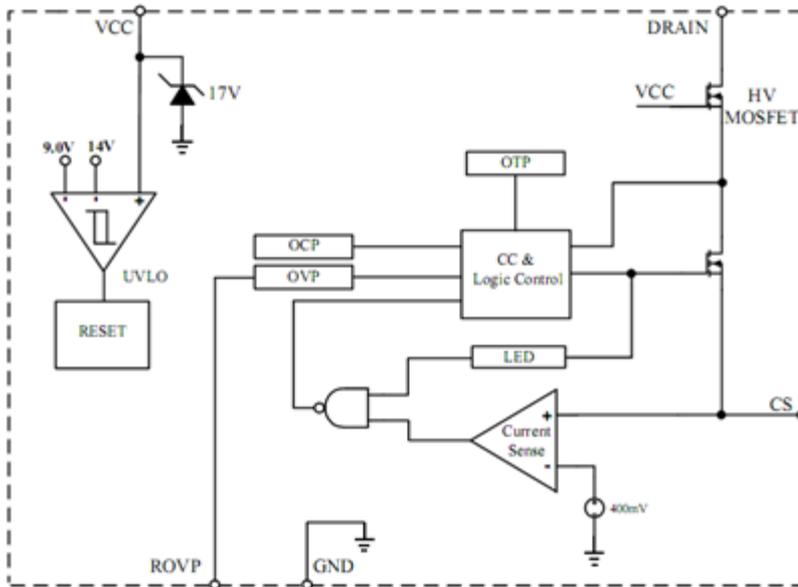


Figure 3. D80221 Internal Block Diagram

## Application Information

The D80221 is a high performance non-isolated Buck converter specially designed for LED lighting. The device integrates a 500V power MOSFET. With very few external components, the converter achieves excellent constant current control. And it does not need auxiliary winding for powering the IC or voltage sensing, hence the system size and cost is greatly reduced.

Single input voltage	Max output current	output efficiency
176-260V ac	150mA	12W

### Start Up

After system powered up, the VCC pin capacitor is charged up by the start up resistor. When the VCC pin voltage reaches the turn on threshold, the internal circuits start operating. The D80221 integrates a 17V zener diode to clamp the VCC voltage. Due to the ultra-low operating current, the auxiliary winding is not needed to supply the IC.

### Constant Current Control

Cycle by Cycle current sense is adopted in D80221, the CS pin is connected to the current sense comparator, and the voltage on CS pin is compared with the internal 400mV reference voltage. The MOSFET will be switched off when the voltage on CS pin reaches the threshold. The CS comparator includes a 350ns leading edge blanking time.

The peak inductor current is given by:

$$I_{PK} = \frac{400}{R_{CS}} \text{ (mA)}$$



Where, RCS is the current sense resistor value.

The current in LED can be calculated by the equation:

$$I_{LED} = \frac{I_{PK}}{2}$$

Where, IPK is the peak current of the inductor.

### Inductor Selection

The D80221 works under inductor current critical conduction mode. When the power MOSFET is switched on, the current in the inductor rises up from zero, the on time of the MOSFET can be calculated by the equation:

$$t_{on} = \frac{L \times I_{PK}}{V_{IN} - V_{LED}}$$

Where, L is the inductance value VIN is the DC bus voltage after the rectifier bridge VLED is the voltage on the LED

After the power MOSFET is switched off, the current in the inductor decreases. When the inductor current reaches zero, the power MOSFET is turned on again by IC internal logic. The off time of the MOSFET is given by:

$$t_{off} = \frac{L \times I_{PK}}{V_{LED}}$$

The inductance can be calculated by the equation:

$$L = \frac{V_{LED} \times (V_{IN} - V_{LED})}{f \times I_{PK} \times V_{IN}}$$

The f is the system switching frequency, which is proportional to the input voltage. So the minimum switching frequency is set at lowest input voltage, and the maximum switching frequency is set at highest input voltage.

The minimum and maximum off time of D80221 is set at 4.5us and 240us, respectively. Referring to the equation of tOFF calculation, if the inductance is too small, the tOFF may be smaller than the minimum off time, system will operate in discontinuous conduction mode and the output current will be smaller than the designed value. If the inductance is too large, the tOFF may be larger than the maximum off time, the system will operate in continuous conduction mode and the output current will be higher than the designed value. So it is important to choose a proper inductance.

### Over Voltage Protection

The over voltage protection can be programmed by the ROVP pin resistor. The ROVP pin voltage is 0.5V.

When the LED is open circuit, the output voltage increases gradually, and the demagnetization time gets shorter. The demagnetization time at OVP---- Tovp can be calculated by the open circuit protection voltage:



$$T_{ovp} \approx \frac{L \times V_{cs}}{R_{cs} \times V_{ovp}}$$

Where  $V_{cs}$  is the CS pin turn off threshold (400mV)  $V_{ovp}$  is the open circuit protection voltage  
And then the  $R_{ovp}$  resistor value can be calculated by the equation:

$$R_{ovp} \approx 15 * T_{ovp} * 10^6 \quad (\text{kohm})$$

## Protection Function

The D80221 offers rich protection functions to improve the system reliability, including LED open/short protection, CS resistor short protection, VCC under voltage protection, thermal regulation. When the LED is open circuit, the system will trigger the over voltage protection and stop switching.

When the LED short circuit is detected, the system works at low frequency (5kHz), and the CS pin turn off threshold is reduced to 200mV. So the system power consumption is very low. At some catastrophic fault condition, such as CS resistor shorted or inductor saturated, the internal fast fault detection circuit will be triggered, the system stops switching immediately.

After the system enters into fault condition, the VCC voltage will decrease until it reaches the UVLO threshold, then the system will re-start again. If the fault condition is removed, the system will recover to normal operation.

## Thermal Regulation

The D80221 integrates thermal regulation function. When the system is over temperature, the output current is gradually reduced; the output power and thermal dissipation are also reduced. The system temperature is regulated and the system reliability is improved. The thermal regulation temperature is set to 150°C internally.

## PCB Layout

The following rules should be followed in D80221 PCB layout: Bypass Capacitor The bypass capacitor on VCC pin should be as close as possible to the VCC Pin and GND pin.

## ROVP Pin

The ROVP resistor should be as close as possible to the ROVP Pin.

## Ground Path

The power ground path for current sense should be short, and the power ground path should be separated from small signal ground path before connecting to the negative node of the bulk capacitor.

## The Area of Power Loop

The area of main current loop should be as small as possible to reduce EMI radiation, such as the inductor, the power MOSFET, the output diode and the bus capacitor loop.

## NC pin

The NC pin should be connected to GND (pin1).

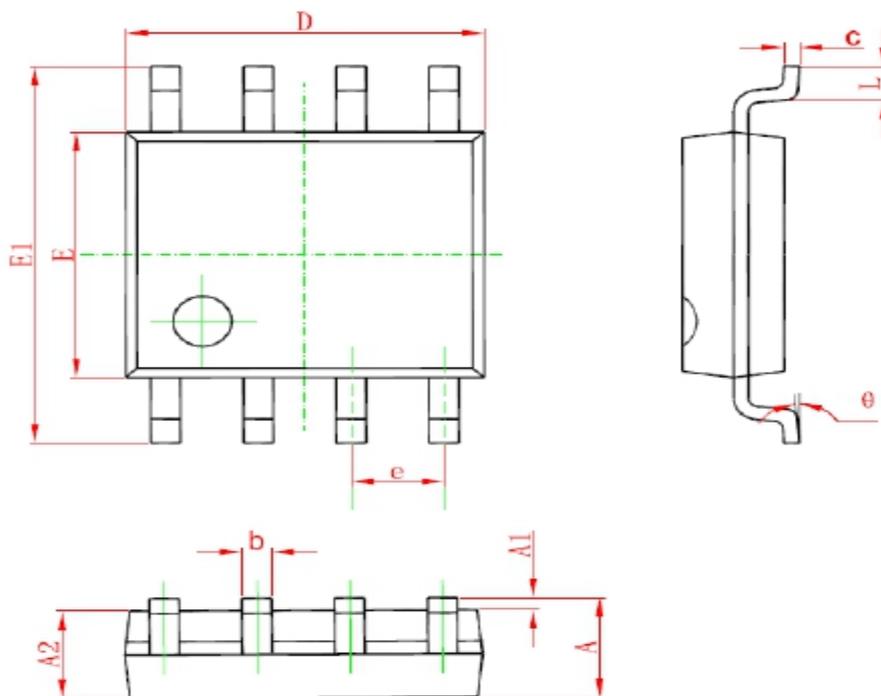
## Drain Pin

To increase the copper area of DRAIN pin for better thermal dissipation. However too large copper area may compromise EMI performance.



## Physical Dimensions

### SOP8 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



日期 Date	版本 Version	说明 Description	排版 Typeset	工程师 Engineer	状态 Status
2014-9-30	A0	/	Jasper	Tracy	Stop
2014-11-26	A1_J	/	Jasper		Active